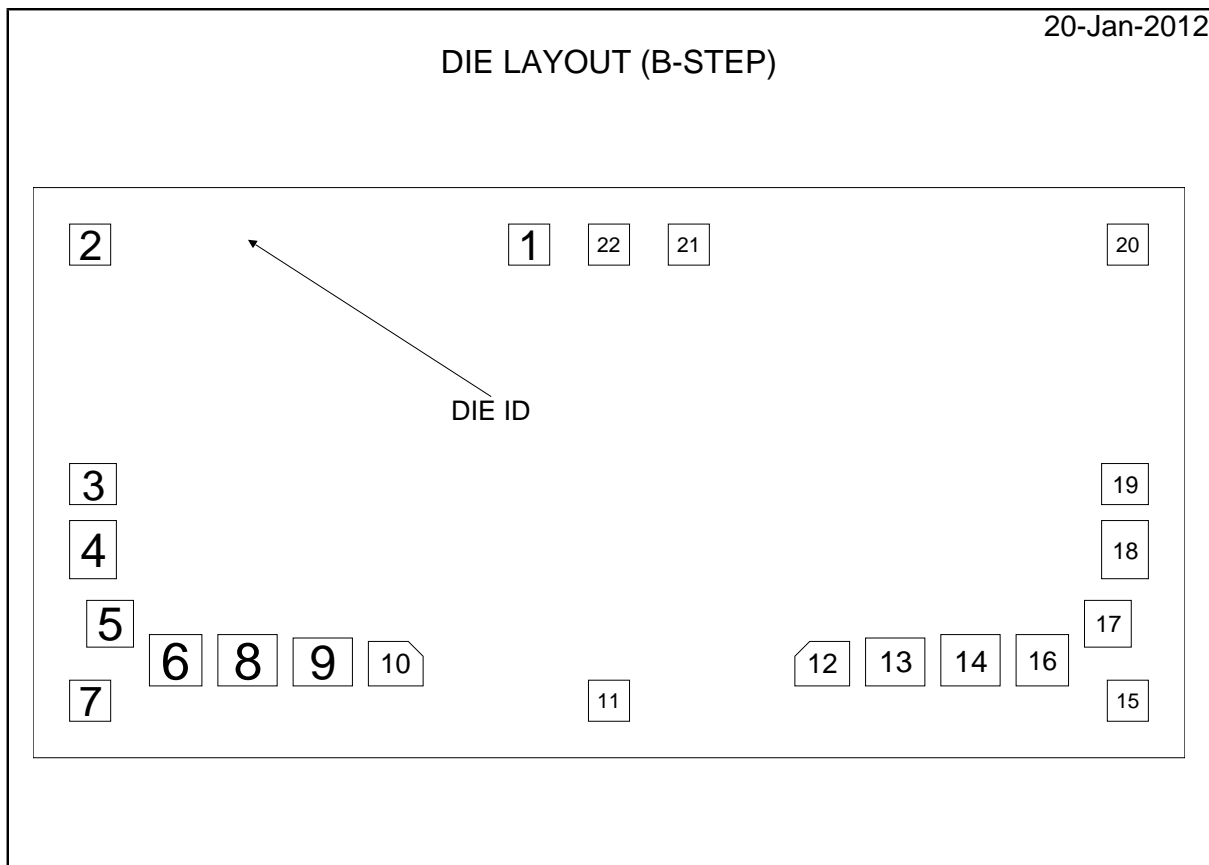


LF442-MD8  
DUAL LOW POWER JFET INPUT OPERATIONAL AMPLIFIER



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LF442	Bond Pad Opening Size (min)	91.44µm x 91.44µm
Die Step	B	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	152.4mm	Back Side Metal	BAREBACK
Die Size (Drawn)	2565.40µm x 1270.00µm 101.0mils x 50.0mils	Back Side Connection	Floating
Thickness	330.0µm Nominal		
Min Pitch	177.80µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

LF442-MD8

DUAL LOW POWER JFET INPUT OPERATIONAL AMPLIFIER

Die Bond Pad Coordinate Locations(B-Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
OUTA	1	-177.80	508.00	91.44	x	91.44
IN A-	2	-1155.70	508.00	91.44	x	91.44
NC	3	-1149.35	-25.40	104.14	x	91.44
NC	4	-1149.35	-171.45	104.14	x	129.54
NC	5	-1111.25	-336.55	104.14	x	104.14
NC	6	-965.20	-417.83	116.84	x	114.30
IN A+	7	-1155.70	-508.00	91.44	x	91.44
NC	8	-805.18	-417.83	132.08	x	114.30
NC	9	-637.54	-421.64	132.08	x	106.68
NC	10	-474.98	-425.45	121.92	x	99.06
V-	11	0.00	-508.00	91.44	x	91.44
NC	12	474.98	-425.45	121.92	x	99.06
NC	13	637.54	-421.64	132.08	x	106.68
NC	14	805.18	-417.83	132.08	x	114.30
IN B+	15	1155.70	-508.00	91.44	x	91.44
NC	16	965.20	-417.83	116.84	x	114.30
NC	17	1111.25	-336.55	104.14	x	104.14
NC	18	1149.35	-171.45	104.14	x	129.54
NC	19	1149.35	-25.40	104.14	x	91.44
IN B-	20	1155.70	508.00	91.44	x	91.44
OUTB	21	177.80	508.00	91.44	x	91.44
V+	22	0.00	508.00	91.44	x	91.44

**LF442-MD8**  
**DUAL LOW POWER JFET INPUT OPERATIONAL AMPLIFIER**

## Notes

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